

Electronic Acknowledgement Receipt

EFS ID:	5531117
Application Number:	10577173
International Application Number:	
Confirmation Number:	1239
Title of Invention:	Semiconductor device with plastic package molding compound, semiconductor chip and leadframe and method for producing the same
First Named Inventor/Applicant Name:	Infineon Technologies AG
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Application Type:	U.S. National Stage under 35 USC 371

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part/.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	SupplIDS.pdf	761670 890ec2f3a30729299a61669639f7fb8ffcabbb3fd	no	4

Warnings:

Information:

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2	Foreign Reference	JP1264230uspto.pdf	372520 1299cae13c28572e579ee2111bfb1415c5 524ed	no	6
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National Stage of an International Application under 35 U.S.C. 371

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New International Application Filed with the USPTO as a Receiving Office

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